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TSMC 2003-1622 IC Package Having Ground IC Chip and Method of Manufacturing Same Tsac et al. Initial Filing 9/22/2004 1/2

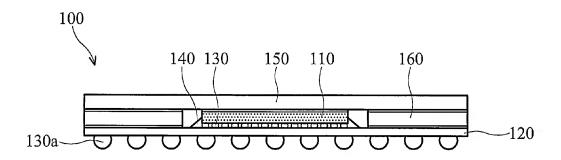


FIGURE 1

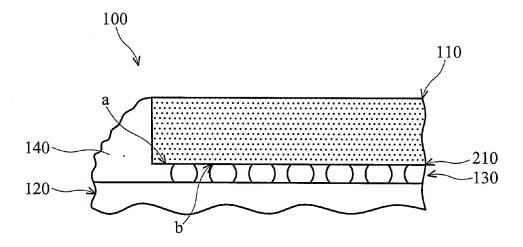


FIGURE 2

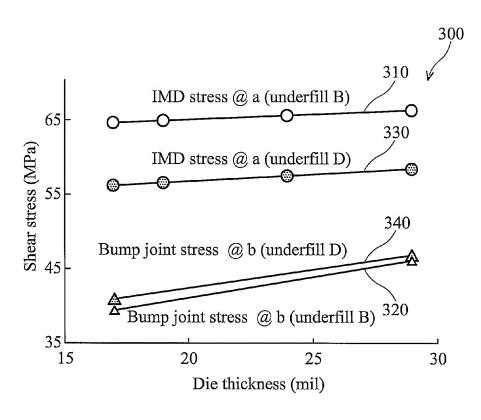


FIGURE 3

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